TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (U-MOSIV)

# **TPCC8008**

Notebook PC Applications Portable Equipment Applications

- Small footprint due to a small and thin package
- Low drain-source ON-resistance:
  - $R_{DS(ON)} = 4.5 \text{ m}\Omega \text{ (typ.)} (V_{GS} = 10 \text{ V})$
- Low leakage current:  $I_{DSS} = 10 \ \mu A \ (max) \ (V_{DS} = 30 \ V)$
- Enhancement mode:  $V_{th}$  = 1.3 to 2.5 V ( $V_{DS}$  = 10 V,  $I_D$  = 1.0 mA)

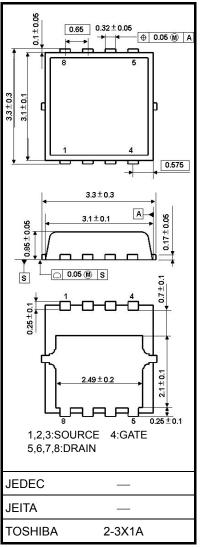
#### Absolute Maximum Ratings (Ta = 25°C)

Characte	eristic	Symbol	Rating	Unit	
Drain-source voltage		V <sub>DSS</sub>	30	V	
Drain-gate voltage (F	R <sub>GS</sub> = 20 kΩ)	V <sub>DGR</sub>	30	V	
Gate-source voltage		V <sub>GSS</sub>	±25	V	
Drain current	DC (Note 1)	۱ <sub>D</sub>	25	٨	
Drain current	Pulsed (Note 1)	I <sub>DP</sub> 75           P <sub>D</sub> 30         V	~		
Drain power dissipati	on (Tc = 25°C)	PD	30	W	
Drain power dissipati	on (t = 10 s) (Note 2a)	PD	1.9	w	
Drain power dissipati	on (t = 10 s) (Note 2b)	PD	0.7	w	
Single-pulse avalanc	he energy (Note 3)	E <sub>AS</sub>	163	mJ	
Avalanche current		I <sub>AR</sub>	25	А	
Repetitive avalanche (To	energy c = 25°C) (Note 4)	E <sub>AR</sub>	2.58	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature	range	T <sub>stg</sub>	–55 to 150	°C	

Note: For Notes 1 to 4, refer to the next page.

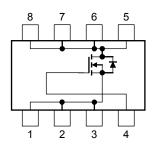
Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

This transistor is an electrostatic-sensitive device. Handle with care.



Weight: 0.02 g (typ.)

#### **Circuit Configuration**



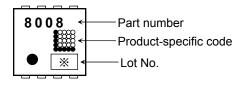
Unit: mm

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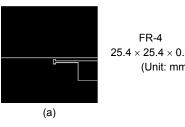
### **Thermal Characteristics**

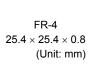
Characteristic	Symbol	Max	Unit
Thermal resistance, channel to case (Tc = 25°C)	R <sub>th (ch-c)</sub>	4.2	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	R <sub>th (ch-a)</sub>	66	°C/W
Thermal resistance, channel to ambient $(t = 10 \text{ s})$ (Note 2b)	R <sub>th (ch-a)</sub>	180	°C/W

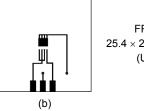
### Marking (Note 5)



- Note 1: Ensure that the channel temperature does not exceed 150°C.
- Note 2: (a) Device mounted on a glass-epoxy board (a)







(b) Device mounted on a glass-epoxy board (b)

FR-4  $25.4\times25.4\times0.8$ (Unit: mm)

- Note 3:  $V_{DD} = 24$  V,  $T_{ch} = 25^{\circ}C$  (initial),  $L = 200 \ \mu$ H,  $R_G = 25 \ \Omega$ ,  $I_{AR} = 25$  A
- Note 4: Repetitive rating: pulse width limited by maximum channel temperature
- Note 5: \* Weekly code: (Three digits)



Week of manufacture (01 for the first week of the year, continuing up to 52 or 53) Year of manufacture

(The last digit of the year)

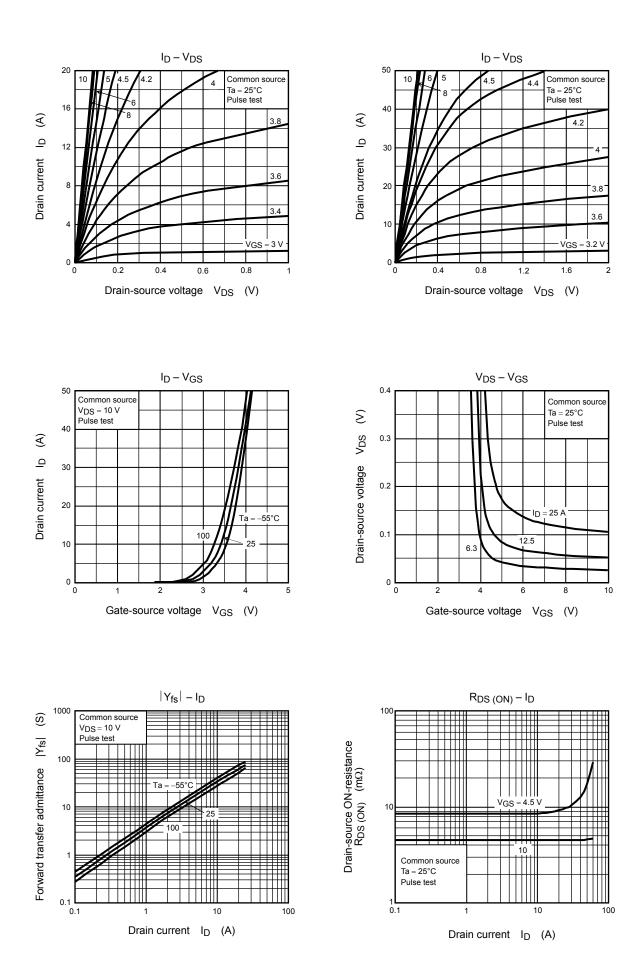
Electrical Characteristics (Ta = 25°C)

Ch	aracteristic	Symbol	Test Condition	Test Condition Min Typ. Ma		Max	Unit
Gate leakage cur	rent	I <sub>GSS</sub>	$V_{GS}=\pm 25~V,~V_{DS}=0~V$	_		±100	nA
Drain cutoff curre	ent	I <sub>DSS</sub>	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	_	_	10	μA
Drain source bro	akdown voltago	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	30		_	V
Drain-source breakdown voltage		V (BR) DSX	$I_D = 10$ mA, $V_{GS} = -20$ V	15	_	—	v
Gate threshold ve	oltage	V <sub>th</sub>	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1.0 \text{ mA}$	1.3	_	2.5	V
	ragistanco		$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 12.5 \text{ A}$	_	8.5	13	m0
Drain-source ON	-Tesistance	RDS (ON)	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 12.5 A	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	mΩ		
Forward transfer	admittance	Y <sub>fs</sub>	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 12.5 \text{ A}$	10 V, I <sub>D</sub> = 12.5 A 22 43			S
Input capacitance	put capacitance		V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	1600	_	pF
Reverse transfer capacitance		C <sub>rss</sub>		_	290	_	
Reverse transfer capacitance Dutput capacitance Rise time Turn-on time Fall time		C <sub>oss</sub>		_	470	_	
	Rise time	tr	10 V 🔲 lp = 12 5 A	_	7.9	_	
Switching time	is       is       is       is         ate leakage current       IGSS $V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$ $\pm 1$ rain cutoff current       IDSS $V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$ 1         rain-source breakdown voltage $V(BR) DSS$ ID = 10 mA, $V_{GS} = 0 \text{ V}$ 30         1         ate threshold voltage $V(th$ $V_{DS} = 10 \text{ V}, ID = 1.0 \text{ mA}$ 1.3        2.2         rain-source ON-resistance $R_{DS}(ON)$ $V_{GS} = 4.5 \text{ V}, ID = 12.5 \text{ A}$ 4.5       6.         onward transfer admittance $ Y_{fs} $ $V_{DS} = 10 \text{ V}, ID = 12.5 \text{ A}$ 4.5       6.         opward transfer capacitance $C_{rss}$ $V_{DS} = 10 \text{ V}, ID = 12.5 \text{ A}$ 4.5       6.         opward transfer capacitance $C_{rss}$ $V_{DS} = 10 \text{ V}, ID = 12.5 \text{ A}$ 4.5       6.         uput capacitance $C_{rss}$ $V_{DS} = 10 \text{ V}, ID = 12.5 \text{ A}$ 4.5       6.         witching time $tr$ $V_{rss}$ $V_{DS} = 0 \text{ V}, f = 1 \text{ MHz}$ 1600 -        -       1600	_					
Switching time	Fall time	t <sub>f</sub>	4.7Ω 4.7Ω		16	_	- ns
	Turn-off time	t <sub>off</sub>		_	42	_	
Total gate charge (gate-source plus					30	_	nC
Gate-source charge 1		Q <sub>gs1</sub>	V <sub>DD</sub> ≈ 24 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 25 A		5.9		
Gate-drain ("Miller") charge		Q <sub>gd</sub>			9.6		

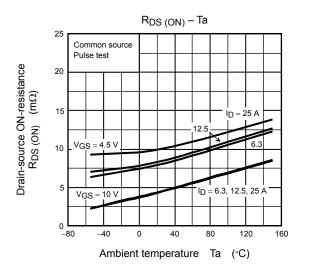
### Source-Drain Ratings and Characteristics (Ta = 25°C)

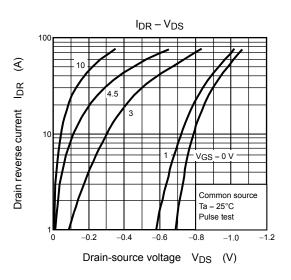
Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit	
Drain reverse current	Pulse	(Note 1)	I <sub>DRP</sub>	—	_	_	75	А
Forward voltage (diode)			V <sub>DSF</sub>	$I_{DR} = 25 \text{ A}, V_{GS} = 0 \text{ V}$	_		-1.2	V

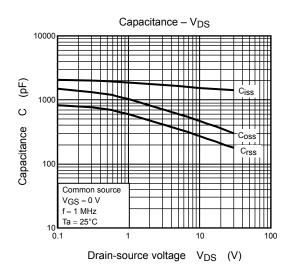
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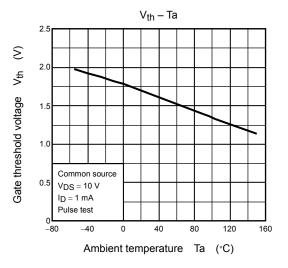


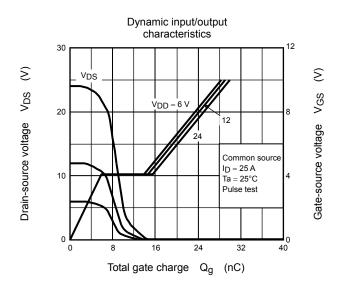
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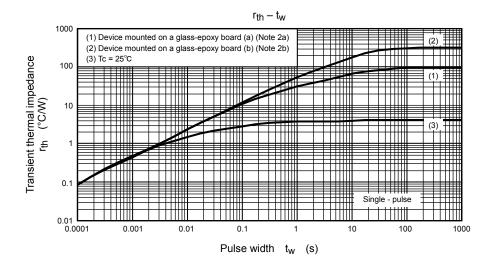


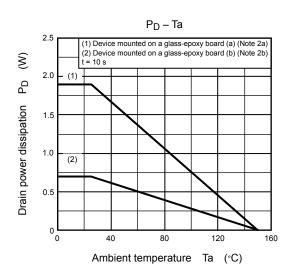


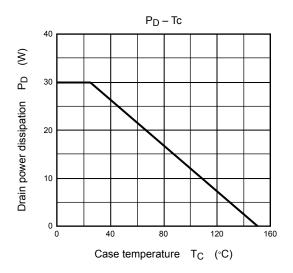


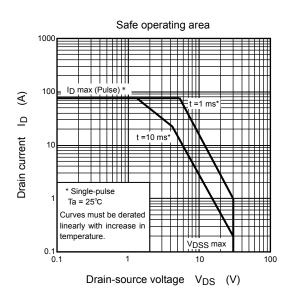












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